

**LIGHT EMITTING DEVICE, METHOD OF MANUFACTURING THE
SAME, AND THIN FILM FORMING APPARATUS**

ABSTRACT OF THE DISCLOSURE

A method of manufacturing a light emitting device of upward emission type and a thin film forming apparatus used in the method are provided. A plurality of film forming chambers are connected to a first transferring chamber. The plural film
5 forming chambers include a metal material evaporation chamber, an EL layer forming chamber, a sputtering chamber, a CVD chamber, and a sealing chamber. By using this thin film forming apparatus, an upward emission type EL element can be fabricated without exposing the element to the outside air. As a result, a highly reliable light emitting device is obtained.

(Fig. 1)